



## Product/Process Change Notice - PCN 18\_0084 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

**PCN Title:** ADuM3211 Die Revision and Assembly Site Transfer

**Publication Date:** 11-May-2018

**Effectivity Date:** 13-Aug-2018 *(the earliest date that a customer could expect to receive changed material)*

### Revision Description:

Initial Release.

### Description Of Change:

Die Changes:

1. Increased pulse width of disable signal for refresh block. Increased separation between falling edge of disable signal for refresh block and first refresh high pulse. Increased separation between consecutive pulses on rising edge and refresh high pulses.
2. Additional layer of polyimide passivation on top of the non-coil die.

Assembly Site Transfer:

1. From Carsem Malaysia to ASE Chungli, Taiwan.

ADI has qualified and will be utilizing assembly subcontractor ASE Chungli, Taiwan for assembly of 8L SOIC\_N Isolator products. ADI has qualified ASE Chungli's standard bill of materials in the SOIC\_N package. See material set changes attachment for details.

### Reason For Change:

Die Changes:

1. Increase manufacturability to ensure continuity of supply.
2. Polyimide offers enhanced protection against die scratches, package stresses and surface ESD/EOS events.

Assembly Site Transfer:

1. To align with ADI's isolator manufacturing strategy. The use of ADI qualified ASE Chungli as an assembly site for this package will ensure continued source of product supply. ADI's assembly subcontractors manufacture our products using Analog Devices specified manufacturing flows, process controls and monitors. This assures that our customers receive the same level of quality and reliability on products they receive from qualified ADI manufacturing locations.

### Impact of the change (positive or negative) on fit, form, function & reliability:

No change to fit, form, or reliability. Improved functionality.

### Summary of Supporting Information:

Qualification has been performed per Industry Standard Test Methods. See attached Qualification Results Summary.

### Supporting Documents

**Attachment 1: Type:** Detailed Change Description

ADI\_PCN\_18\_0084\_Rev\_-\_Material Set Changes SOIC\_N of Isolator at ASE CHUNGLI.pdf

**Attachment 2: Type:** Qualification Results Summary

ADI\_PCN\_18\_0084\_Rev\_-\_Qualification\_Results\_Summary\_ADuM3211.pdf

**For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.**

**Americas:**  
PCN\_Americas@analog.com

**Europe:**  
PCN\_Europe@analog.com

**Japan:**  
PCN\_Japan@analog.com

**Rest of Asia:**  
PCN\_ROA@analog.com

**Appendix A - Affected ADI Models**

**Added Parts On This Revision - Product Family / Model Number (6)**

ADUM3211 / ADUM3211ARZ	ADUM3211 / ADUM3211ARZ-RL7	ADUM3211 / ADUM3211BRZ	ADUM3211 / ADUM3211BRZ-RL7	ADUM3211 / ADUM3211TRZ
ADUM3211 / ADUM3211TRZ-RL7				

**Appendix B - Revision History**

<b>Rev</b>	<b>Publish Date</b>	<b>Effectivity Date</b>	<b>Rev Description</b>
Rev. -	11-May-2018	13-Aug-2018	Initial Release.

Analog Devices, Inc.

DocId:4428 Parent DocId:4366 Layout Rev:7